



**AO6405**

**P-Channel Enhancement Mode Field Effect Transistor**

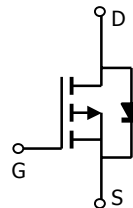
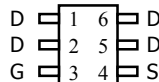
**General Description**

The AO6405 uses advanced trench technology to provide excellent  $R_{DS(ON)}$  with low gate charge. This device is suitable for use as a load switch or in PWM applications.

**Features**

- $V_{DS} (V) = -30V$
- $I_D = -5 A$
- $R_{DS(ON)} < 52m\Omega (V_{GS} = -10V)$
- $R_{DS(ON)} < 87m\Omega (V_{GS} = -4.5V)$

**TSOP6  
Top View**



**Absolute Maximum Ratings  $T_A=25^\circ C$  unless otherwise noted**

| Parameter                              | Symbol         | Maximum          | Units      |
|--|----------------|------------------|------------|
| Drain-Source Voltage                   | $V_{DS}$       | -30              | V          |
| Gate-Source Voltage                    | $V_{GS}$       | $\pm 20$         | V          |
| Continuous Drain Current <sup>A</sup>  | $I_D$          | $T_A=25^\circ C$ | -5         |
|  |                | $T_A=70^\circ C$ | -4.2       |
| Pulsed Drain Current <sup>B</sup>      | $I_{DM}$       | -20              | A          |
| Power Dissipation <sup>A</sup>         | $P_D$          | $T_A=25^\circ C$ | 2          |
|  |                | $T_A=70^\circ C$ | 1.4        |
| Junction and Storage Temperature Range | $T_J, T_{STG}$ | -55 to 150       | $^\circ C$ |

**Thermal Characteristics**

| Parameter                                | Symbol          | Typ          | Max  | Units        |
|--|-----------------|--------------|------|--------------|
| Maximum Junction-to-Ambient <sup>A</sup> | $R_{\theta JA}$ | $t \leq 10s$ | 47.5 | $^\circ C/W$ |
| Maximum Junction-to-Ambient <sup>A</sup> |                 | Steady-State | 74   | $^\circ C/W$ |
| Maximum Junction-to-Lead <sup>C</sup>    | $R_{\theta JL}$ | 37           | 50   | $^\circ C/W$ |

Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)

| Symbol                      | Parameter                             | Conditions  | Min | Typ      | Max       | Units            |
|-----------------------------|---------------------------------------|---|-----|----------|-----------|------------------|
| <b>STATIC PARAMETERS</b>    |                                       |   |     |          |           |                  |
| $BV_{DSS}$                  | Drain-Source Breakdown Voltage        | $I_D=-250\mu\text{A}, V_{GS}=0\text{V}$                                     | -30 |          |           | V                |
| $I_{DSS}$                   | Zero Gate Voltage Drain Current       | $V_{DS}=-24\text{V}, V_{GS}=0\text{V}$<br>$T_J=55^\circ\text{C}$            |     |          | -1<br>-5  | $\mu\text{A}$    |
| $I_{GSS}$                   | Gate-Body leakage current             | $V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$                                   |     |          | $\pm 100$ | nA               |
| $V_{GS(th)}$                | Gate Threshold Voltage                | $V_{DS}=V_{GS}, I_D=-250\mu\text{A}$  | -1  | -1.8     | -3        | V                |
| $I_{D(ON)}$                 | On state drain current                | $V_{GS}=-4.5\text{V}, V_{DS}=-5\text{V}$                                    | -10 |          |           | A                |
| $R_{DS(ON)}$                | Static Drain-Source On-Resistance     | $V_{GS}=-10\text{V}, I_D=5.0\text{A}$<br>$T_J=125^\circ\text{C}$            |     | 39<br>54 | 52<br>70  | $\text{m}\Omega$ |
|                             |                                       | $V_{GS}=-4.5\text{V}, I_D=-4\text{A}$                                       |     | 67       | 87        | $\text{m}\Omega$ |
| $g_{FS}$                    | Forward Transconductance              | $V_{DS}=-5\text{V}, I_D=-5\text{A}$   | 6   | 8.6      |           | S                |
| $V_{SD}$                    | Diode Forward Voltage                 | $I_S=-1\text{A}, V_{GS}=0\text{V}$  |     | -0.77    | -1        | V                |
| $I_S$                       | Maximum Body-Diode Continuous Current |   |     |          | -2.8      | A                |
| <b>DYNAMIC PARAMETERS</b>   |                                       |   |     |          |           |                  |
| $C_{iss}$                   | Input Capacitance                     | $V_{GS}=0\text{V}, V_{DS}=-15\text{V}, f=1\text{MHz}$                       |     | 700      |           | pF               |
| $C_{oss}$                   | Output Capacitance                    |   |     | 120      |           | pF               |
| $C_{rss}$                   | Reverse Transfer Capacitance          |   |     | 75       |           | pF               |
| $R_g$                       | Gate resistance                       | $V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$                         |     | 10       |           | $\Omega$         |
| <b>SWITCHING PARAMETERS</b> |                                       |   |     |          |           |                  |
| $Q_g(10\text{V})$           | Total Gate Charge (10V)               | $V_{GS}=-10\text{V}, V_{DS}=-15\text{V}, I_D=-5\text{A}$                    |     | 14.7     |           | nC               |
| $Q_g(4.5\text{V})$          | Total Gate Charge (4.5V)              |   |     | 7.6      |           | nC               |
| $Q_{gs}$                    | Gate Source Charge                    |   |     | 2        |           | nC               |
| $Q_{gd}$                    | Gate Drain Charge                     |   |     | 3.8      |           | nC               |
| $t_{D(on)}$                 | Turn-On Delay Time                    | $V_{GS}=-10\text{V}, V_{DS}=-15\text{V}, R_L=3\Omega,$<br>$R_{GEN}=3\Omega$ |     | 8.3      |           | ns               |
| $t_r$                       | Turn-On Rise Time                     |   |     | 5        |           | ns               |
| $t_{D(off)}$                | Turn-Off Delay Time                   |   |     | 29       |           | ns               |
| $t_f$                       | Turn-Off Fall Time                    |   |     | 14       |           | ns               |
| $t_{rr}$                    | Body Diode Reverse Recovery Time      | $I_F=-5\text{A}, dI/dt=100\text{A}/\mu\text{s}$                             |     | 23.5     |           | ns               |
| $Q_{rr}$                    | Body Diode Reverse Recovery Charge    | $I_F=-5\text{A}, dI/dt=100\text{A}/\mu\text{s}$                             |     | 13.4     |           | nC               |

A: The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The value in any a given application depends on the user's specific board design. The current rating is based on the  $t \leq 10\text{s}$  thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C: The  $R_{\theta JA}$  is the sum of the thermal impedance from junction to lead  $R_{\theta JL}$  and lead to ambient.

D: The static characteristics in Figures 1 to 6, 12, 14 are obtained using 80 $\mu\text{s}$  pulses, duty cycle 0.5% max.

E: These tests are performed with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The SOA curve provides a single pulse rating.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

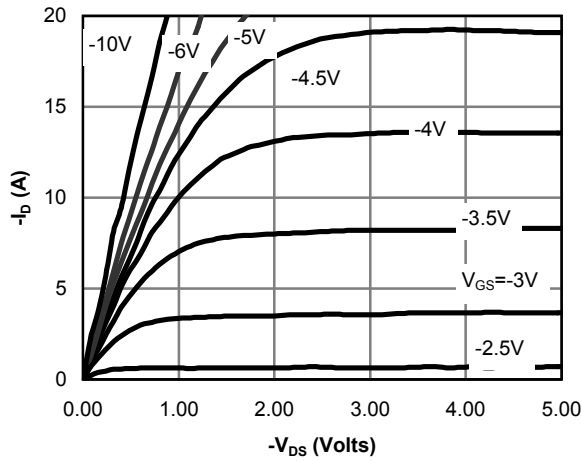


Figure 1: On-Region Characteristics

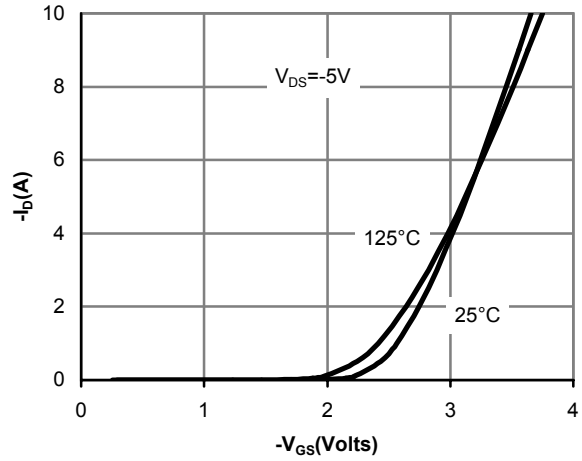


Figure 2: Transfer Characteristics

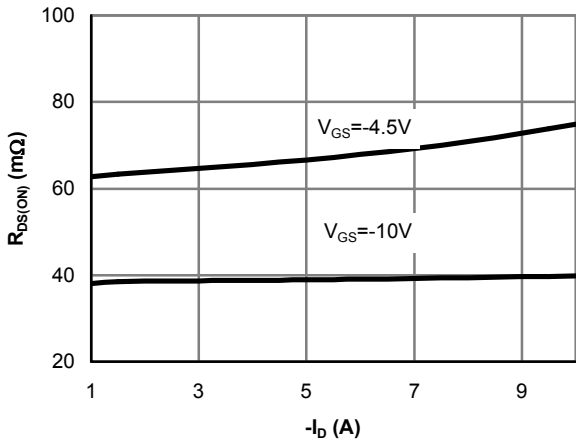


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

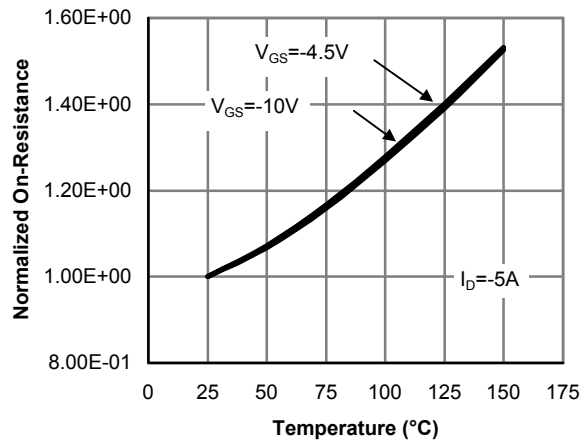


Figure 4: On-Resistance vs. Junction Temperature

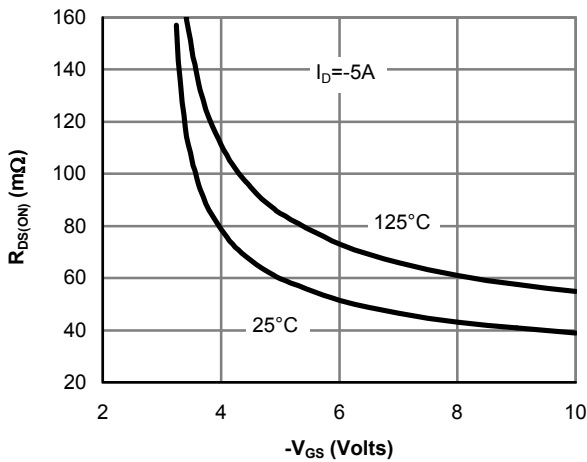


Figure 5: On-Resistance vs. Gate-Source Voltage

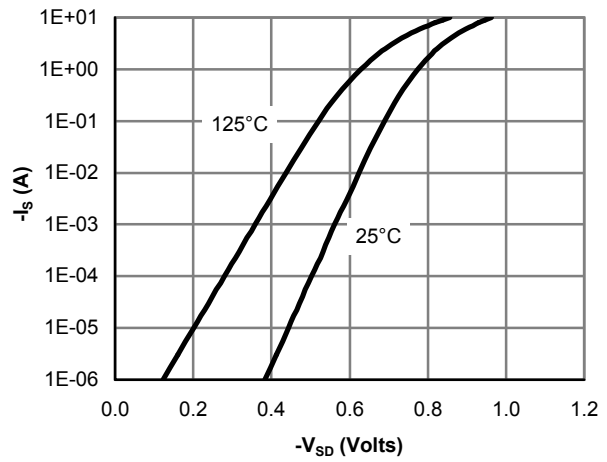


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

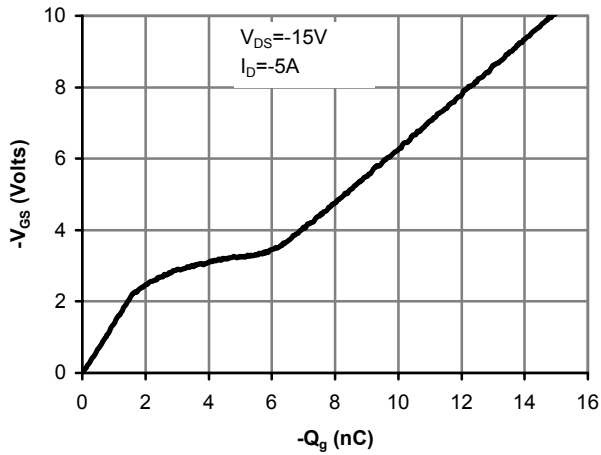


Figure 7: Gate-Charge Characteristics

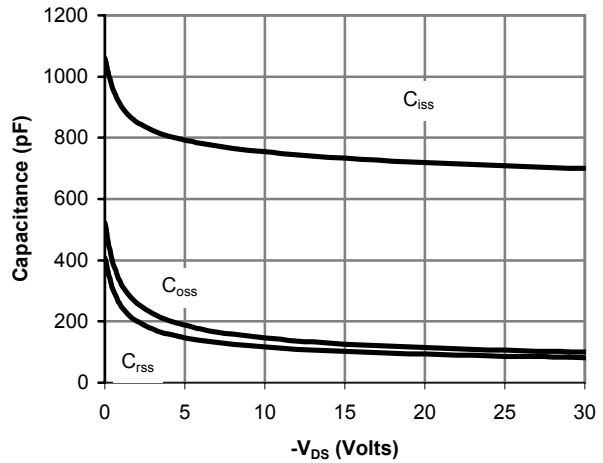


Figure 8: Capacitance Characteristics

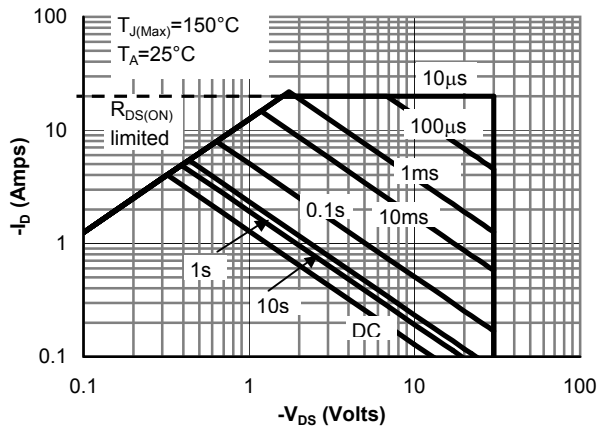


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

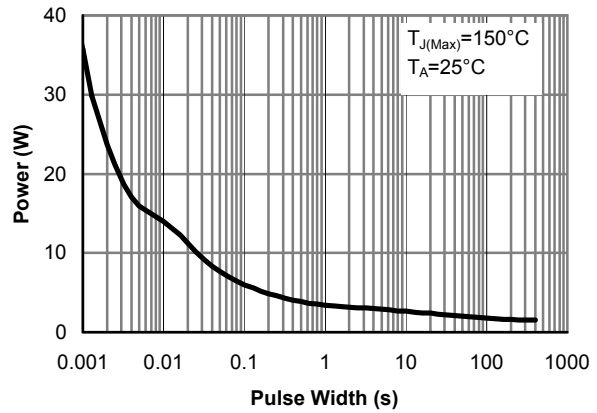


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

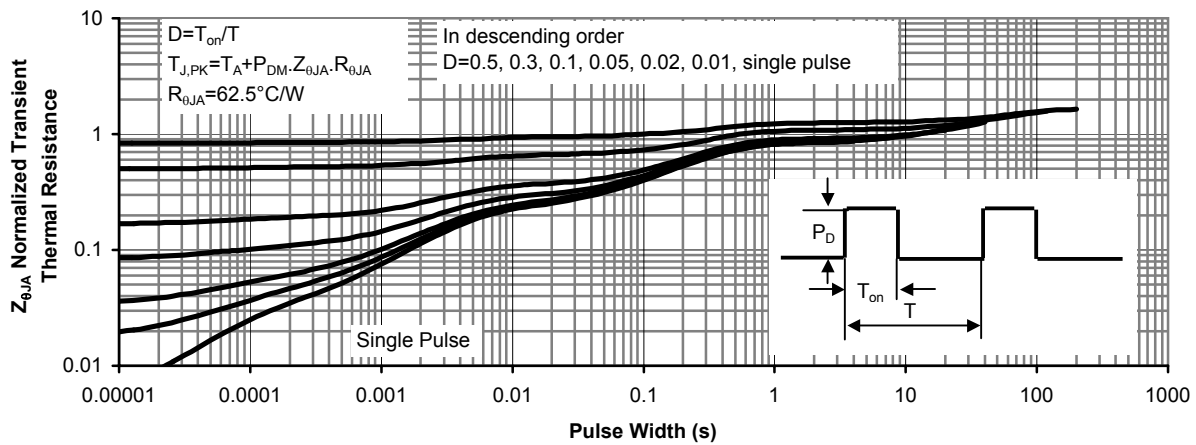
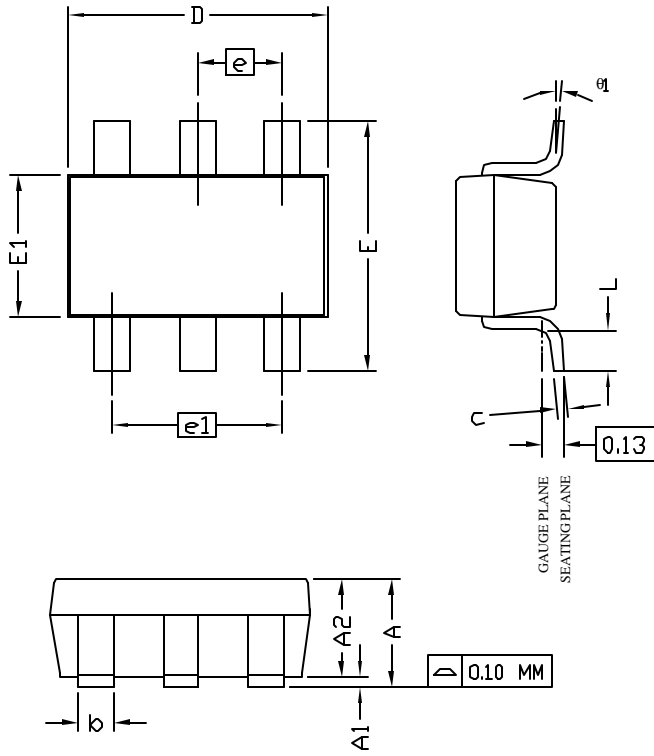


Figure 11: Normalized Maximum Transient Thermal Impedance



**ALPHA & OMEGA**  
SEMICONDUCTOR, INC.

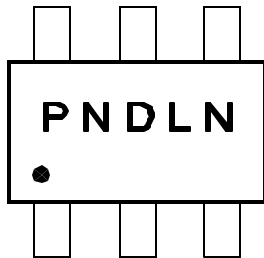
## TSOP-6 Package Data



| SYMBOLS    | DIMENSIONS IN MILLIMETERS |      |      |
|------------|---------------------------|------|------|
|            | MIN                       | NOM  | MAX  |
| A          | 1.00                      | —    | 1.25 |
| A1         | 0.00                      | —    | 0.10 |
| A2         | 1.00                      | 1.10 | 1.15 |
| b          | 0.35                      | 0.40 | 0.50 |
| c          | 0.10                      | 0.13 | 0.20 |
| D          | 2.70                      | 2.90 | 3.10 |
| E          | 2.60                      | 2.80 | 3.00 |
| E1         | 1.60                      | 1.80 | 2.00 |
| e          | 0.95 BSC                  |      |      |
| e1         | 1.90 BSC                  |      |      |
| L          | 0.37                      | —    | —    |
| $\theta 1$ | 1°                        | 5°   | 8°   |

- NOTE:
- LEAD FINISH: 150 MICRONS (3.8  $\mu$ m) MIN. THICKNESS OF Tin/Lead (SOLDER) PLATED ON LEAD
  - TOLERANCE  $\pm 0.100$  mm (4 mil) UNLESS OTHERWISE SPECIFIED
  - COPLANARITY : 0.1000 mm
  - DIMENSION L IS MEASURED IN GAGE PLANE

### PACKAGE MARKING DESCRIPTION

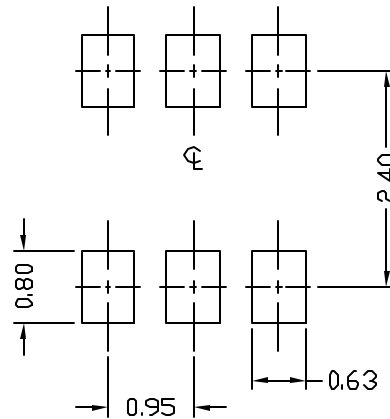


### TSOP-6 PART NO. CODE

| PART NO. | CODE |
|----------|------|
| AO6405   | D5   |
|          |      |

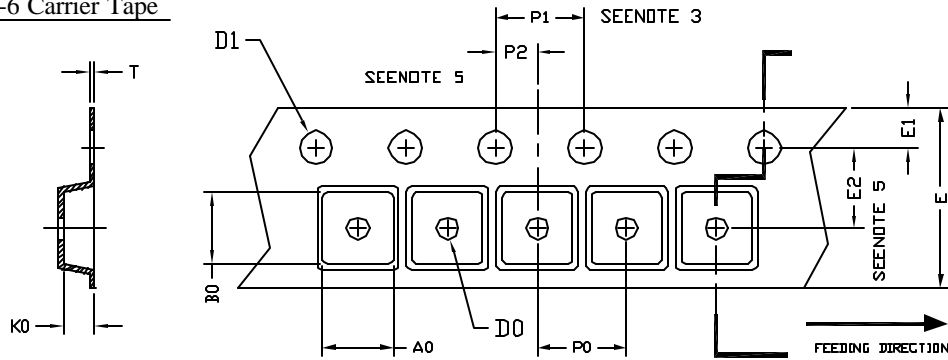
- NOTE:
- P N - PART NUMBER CODE.
  - D - YEAR AND WEEK CODE.
  - L N - ASSEMBLY LOT CODE, FAB AND ASSEMBLY LOCATION CODE.

### RECOMMENDED LAND PATTERN





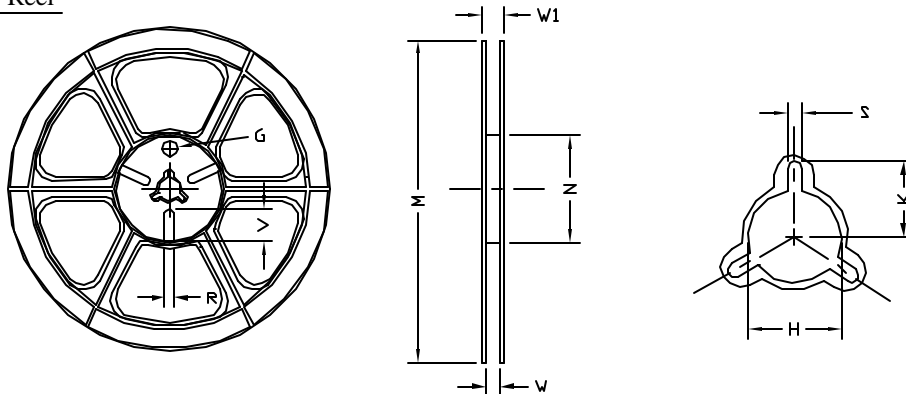
TSOP-6 Carrier Tape



UNIT: MM

| PACKAGE          | A0            | B0            | K0            | D0            | D1            | E             | E1            | E2            | P0            | P1            | P2            | T             |
|------------------|---------------|---------------|---------------|---------------|---------------|---------------|---------------|---------------|---------------|---------------|---------------|---------------|
| SDT-23<br>(8 mm) | 3.15<br>±0.10 | 3.27<br>±0.10 | 1.34<br>±0.10 | 1.10<br>±0.01 | 1.30<br>±0.10 | 8.00<br>±0.20 | 1.75<br>±0.10 | 3.50<br>±0.05 | 4.00<br>±0.10 | 4.00<br>±0.10 | 2.00<br>±0.10 | 0.25<br>±0.05 |

TSOP-6 Reel



UNIT: MM

| TAPE SIZE | REEL SIZE | M                | N      | W             | W1             | H                        | K     | S             | G     | R    | V     |
|-----------|-----------|------------------|--------|---------------|----------------|--------------------------|-------|---------------|-------|------|-------|
| 8 mm      | φ180      | φ180.00<br>±0.50 | φ60.50 | 9.00<br>±0.30 | 11.40<br>±1.00 | φ13.00<br>+0.50<br>-0.20 | 10.60 | 2.00<br>±0.50 | φ9.00 | 5.00 | 18.00 |

TSOP-6 Tape

Leader / Trailer  
& Orientation

